18/11/03
20030695?2

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
24 July 2003 (24.07.2003)

PCT

(10) International Publication Number
WO 03/060028 A1

(51) International Patent Classification[7]: C09G 1/02, H01L 21/304

(21) International Application Number: PCT/US02/40504

(22) International Filing Date:
17 December 2002 (17.12.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/032,049 21 December 2001 (21.12.2001) US

(71) Applicant: MICRON TECHNOLOGY, INC. [US/US]; 8000 South Federal Way, Boise, ID 83707-0006 (US).

(72) Inventor: VAARTSTRA, Brian, A.; 3417 Braden Lane, Nampa, ID 83686 (US).

(74) Agent: MUETING, Ann, M.; Mueting, Raasch & Gebhardt, P.A., P.O. Box 581415, Minneapolis, MN 55458-1415 (US).

(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.



162162



ACTION

WO 03/060028 A1

(54) Title: METHODS FOR PLANARIZATION OF METAL-CONTAINING SURFACES USING HALOGENS AND HALIDE SALTS

(57) Abstract: A planarization method includes providing a metal-containing surface (preferably, a Group VIII metal-containing surface, and more preferably a platinum-containing surface) and positioning it for contact with a polishing surface in the presence of a planarization composition that includes a halogen and a halide salt.